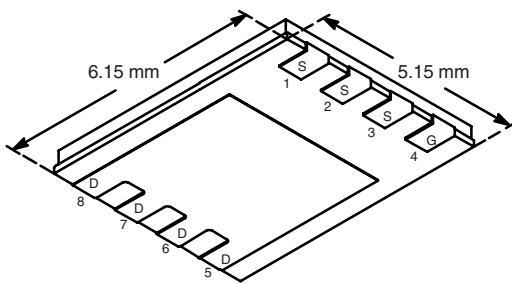


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ.)
30	0.0040 at $V_{GS} = 10$ V	25	47
	0.0048 at $V_{GS} = 4.5$ V	23	

PowerPAK SO-8



Bottom View

Ordering Information: Si7886ADP-T1-E3 (Lead (Pb)-free)
Si7886ADP-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

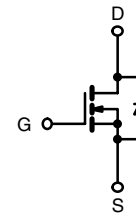
- Halogen-free available
- TrenchFET® Power MOSFET
- Optimized for “Low Side” Synchronous Rectifier Operation
- New Low Thermal Resistance PowerPAK® Package with Low 1.07 mm Profile
- 100 % R_g Tested



RoHS
COMPLIANT

FEATURES

- DC/DC Converters
- Synchronous Rectifiers



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	± 12		
Continuous Drain Current ($T_J = 150\text{ }^{\circ}\text{C}$) ^a	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	25	15	A
	$T_A = 70\text{ }^{\circ}\text{C}$		20	12	
Pulsed Drain Current (10 μs Pulse Width)		I_{DM}	60		
Continuous Source Current (Diode Conduction) ^a		I_S	4.5	1.6	
Avalanche Current	L = 0.1 mH	I_{AS}	50		mJ
Single Pulse Avalanche Energy		E_{AS}	125		
Maximum Power Dissipation ^a	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	5.4	1.9	W
	$T_A = 70\text{ }^{\circ}\text{C}$		3.4	1.2	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150		$^{\circ}\text{C}$
Soldering Recommendations (Peak Temperature) ^{b, c}			260		

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	18	23	$^\circ\text{C/W}$
		50	65	
Maximum Junction-to-Case (Drain)	R_{thJC}	1.0	1.5	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. See Solder Profile (<http://www.vishay.com/ppg?73257>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

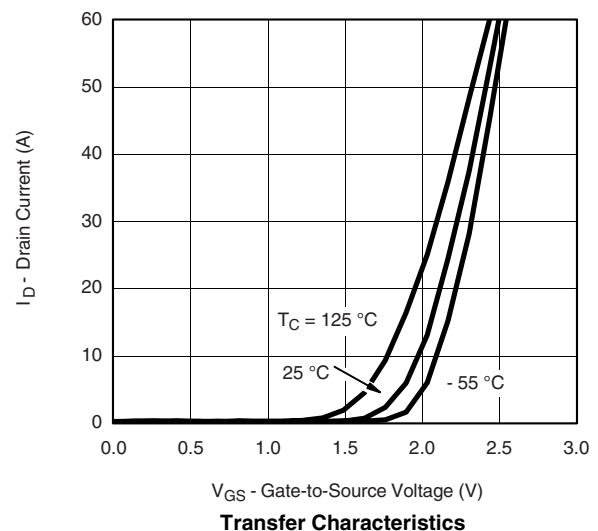
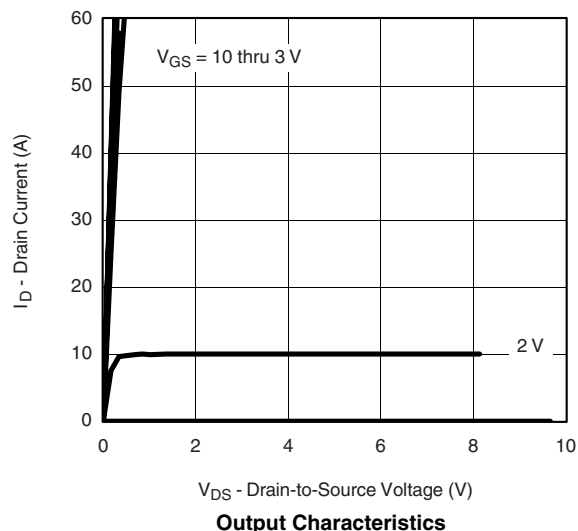
SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	0.6	1	1.5	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 12\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 30\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^{\circ}\text{C}$			5	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}$, $V_{GS} = 10\text{ V}$	30			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 25\text{ A}$		0.0032	0.0040	Ω
		$V_{GS} = 4.5\text{ V}$, $I_D = 23\text{ A}$		0.0037	0.0048	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}$, $I_D = 25\text{ A}$		90		S
Diode Forward Voltage ^a	V_{SD}	$I_S = 2.9\text{ A}$, $V_{GS} = 0\text{ V}$		0.7	1.1	V
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = 15\text{ V}$, $V_{SS} = 0\text{ V}$, $f = 1\text{ kHz}$		6450		pF
Output Capacitance	C_{oss}			873		
Reverse Transfer Capacitance	C_{rss}			402		
Total Gate Charge	Q_g	$V_{DS} = 15\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 25\text{ A}$		47	60	nC
Gate-Source Charge	Q_{gs}			12.5		
Gate-Drain Charge	Q_{gd}			9.0		
Gate Resistance	R_g		0.5	1.0	1.5	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}$, $R_L = 15\text{ }\Omega$ $I_D \cong 1.0\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_G = 6\text{ }\Omega$		17	30	ns
Rise Time	t_r			14	25	
Turn-Off Delay Time	$t_{d(off)}$			158	230	
Fall Time	t_f			43	65	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 2.9\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$		50	80	

Notes:

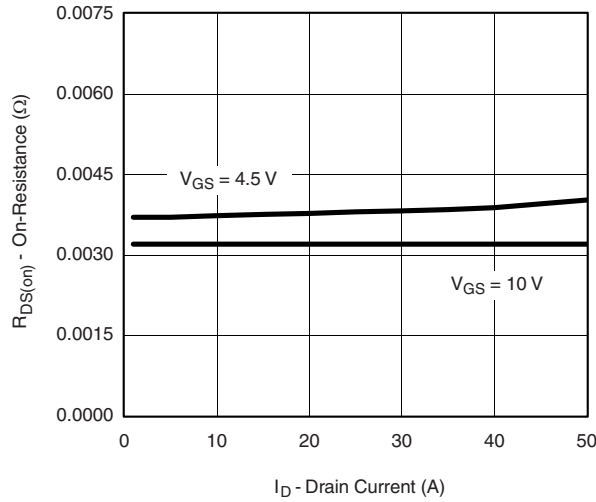
a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

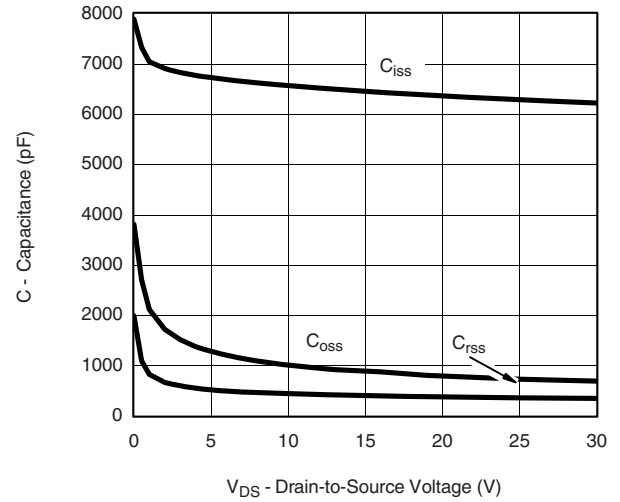
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS $25\text{ }^{\circ}\text{C}$, unless otherwise noted

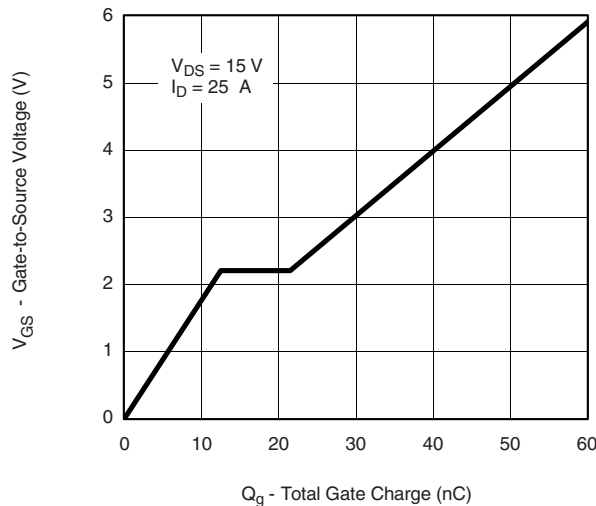
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



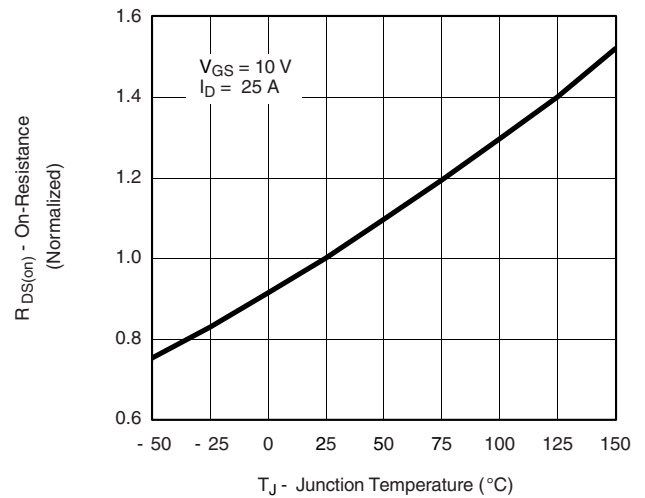
On-Resistance vs. Drain Current



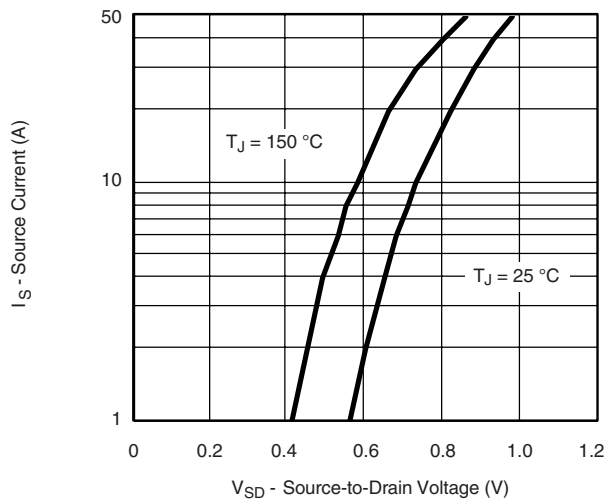
Capacitance



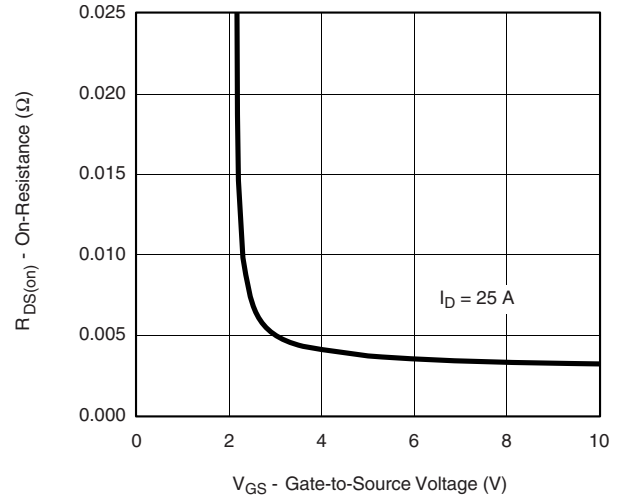
Gate Charge



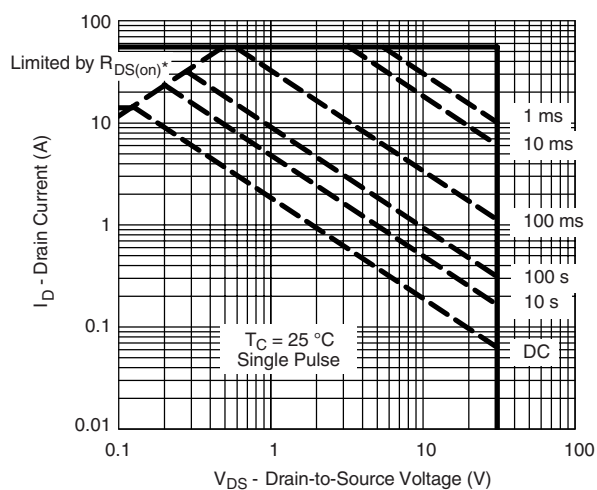
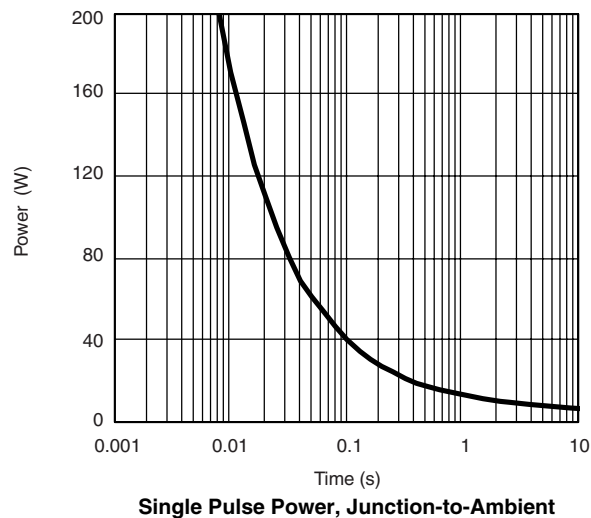
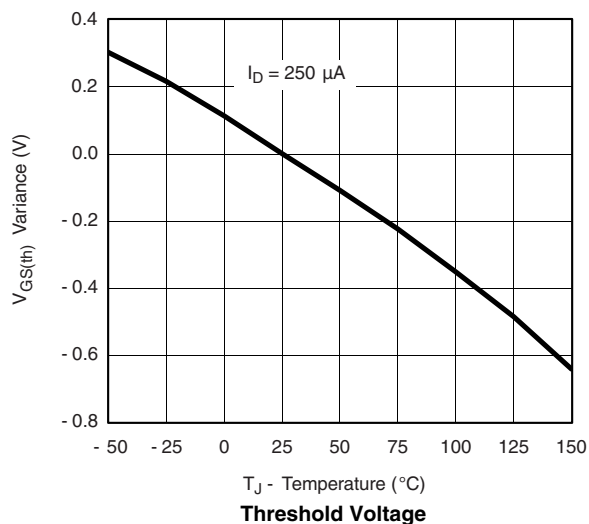
On-Resistance vs. Junction Temperature



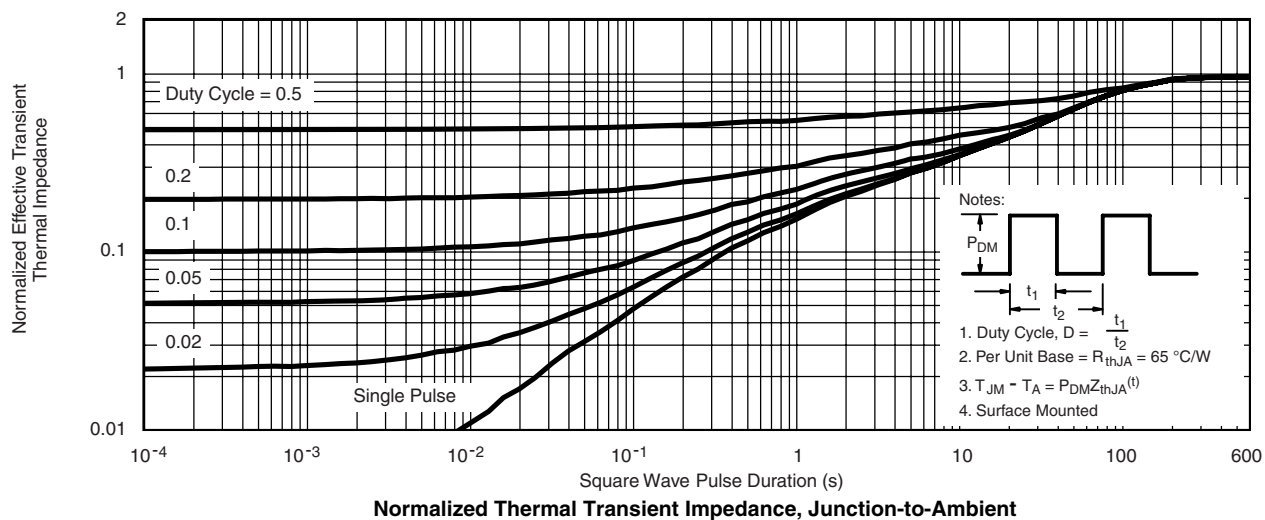
Source-Drain Diode Forward Voltage



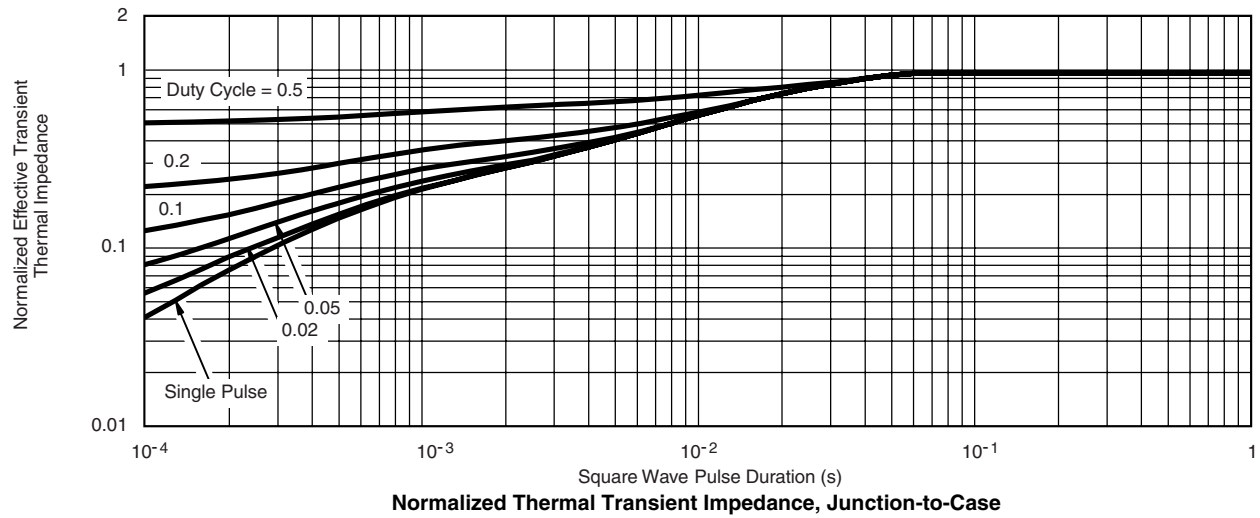
On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Case

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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